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(54) Title: GOLD CONTAINING DIE BOND SHEET PREFORM SPOT-WELDED TO A SEMICONDUCTOR BOND SITE ON A SEMICONDUCTOR PACKAGE AND CORRESPONDING MANUFACTURING METHOD

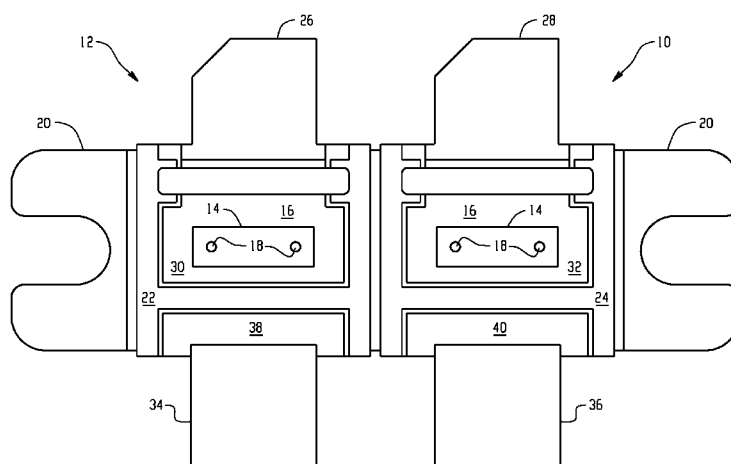


Fig. 1

(57) Abstract: The amount of gold required for solder bonding a semiconductor die (52, 54) to an electronic package (12) is reduced by using a sheet preform (14) tack (spot) welded to the package (12) prior to mounting the die (52, 54). The preform (14), only slightly larger than a semiconductor die (52, 54) to be attached to the package (12), is placed in the die bond location (16) and tack (spot) welded to the package (12) at two spaced locations (18). The preform (14) comprises gold or a gold alloy such as AuSn or AuGe.

